

GENERAL PURPOSE ADHESIVES

EPOXIBOND - General-purpose adhesives are used for bonding, sealing, and repairing wide variety of materials including metals, most plastics, and wood. The fully cured products provide excellent dielectric properties, and very good thermal shock & impact resistance. They also have good resistance to weather, water, most petroleum products, mild acids & alkalis, and many other chemicals.

EPOXIBOND		EB-102F	EB-103F	EB-116	EB-118	EB-216	EB-316TM
Hardener		EH-14	EH-1	EH-116	EH-9	EH-216	PART-B
FEATURES		High bond strength	Fast Cure	High peel strength	High bond strength	Thixotropic High peel strength	High bond and peel strength
Mix ratio by weight (Epoxibond/Hardener)		100/100	100/100	100/100	100/10	100/100	100/100
Mix Viscosity @ 25°C	cps	15,000	5000	5000	5000	Paste	Paste
Pot life @ 25°C	100 grams	2 hr @ 25°C	15 minutes @ 25°C	2 hrs @ 25°C	3/4 hr @ 25°C	2 hrs @ 25°C	2 hr @ 25°C
Shelf Life	@ 25°C	2 years	2 years	2 years	2 years	2 years	2 years
Recommended Cure		24 hrs @ 25°C	24 hrs @ 25°C	2 hrs @ 65°C	2 hrs @ 65°C	24 hrs @ 25°C	24 hrs @ 25°C
Alternate Cure		2 hrs @ 100°C	2 hrs @ 70°C	24 hr @ 25°C	24 hrs @ 25°C	½ hr @100°C	½ hr @100°C+ 1 hr @ 150°C
TYPICAL CURED PROPERTIES							
Color		Clear Amber	Clear	Black	Milky White	Milky White	Black
Specific Gravity		1.1	1.1	1.1	1.1	1.1	1.35
Hardness	Shore D	82	65	72	85	72	91
Lap shear strength	psi	3500	2350	3200	4560	3200	4200
Glass Transition Temperature	°C	70	40	50	90	50	105
Coefficient of Thermal Expansion	10 ⁻⁶ /°C	68	135	94	66	94	77
Service Temperature Range	°C	-55°C to 120°C	-55°C to 120°C	-55°C to 110°C	-55°C to 110°C	-55°C to 110°C	-55°C to 150°C
Dielectric Strength (3mm thickness)	Volts/mil	410	600	380	380	380	410
Dielectric Constant	@ 1 kHz	2.92	3.2	3.81	3.5	3.81	4.28
Dissipation Factor	@ 1 kHz	0.006	0.03	0.4	0.008	0.4	0.4
Volume Resistivity	Ohm-cm	2x10 ¹⁶	1x10 ¹⁵	2x10 ¹³	2x10 ¹⁵	2x10 ¹³	3x10 ¹⁴